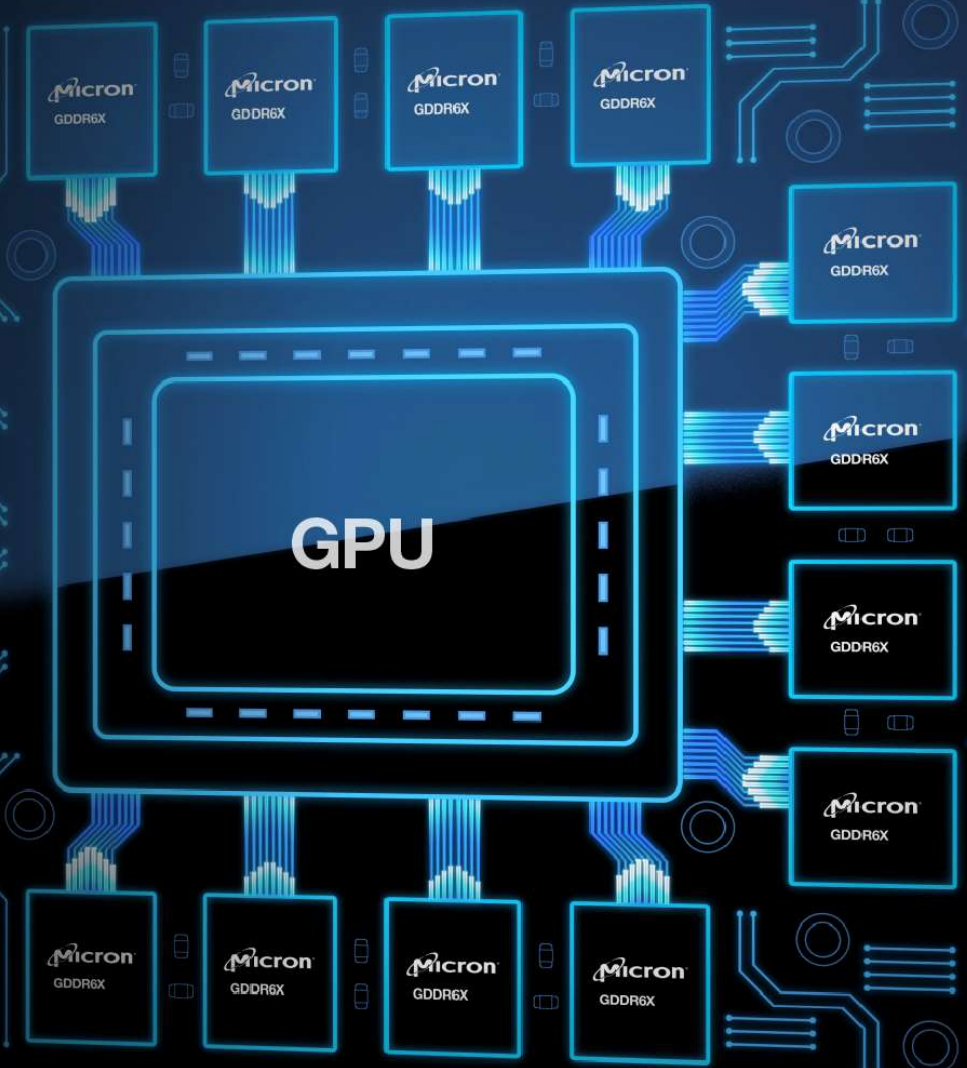




GDDR6X

Memory Reimagined

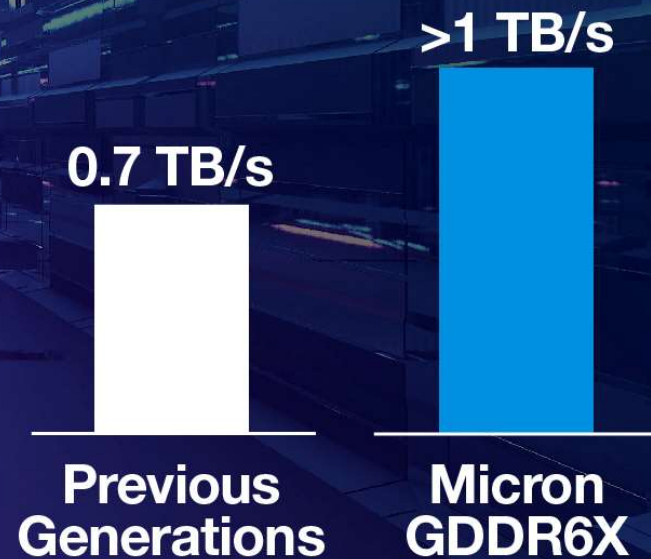
Micron's GDDR6X memory uses innovative signaling technology to double the data rate, delivering unprecedented graphics memory performance to feed the most data-hungry workloads.



Faster. Smoother.

To achieve this breakthrough, Micron has applied innovative signal transmission technology (PAM4) to completely reimagine how memory moves data.

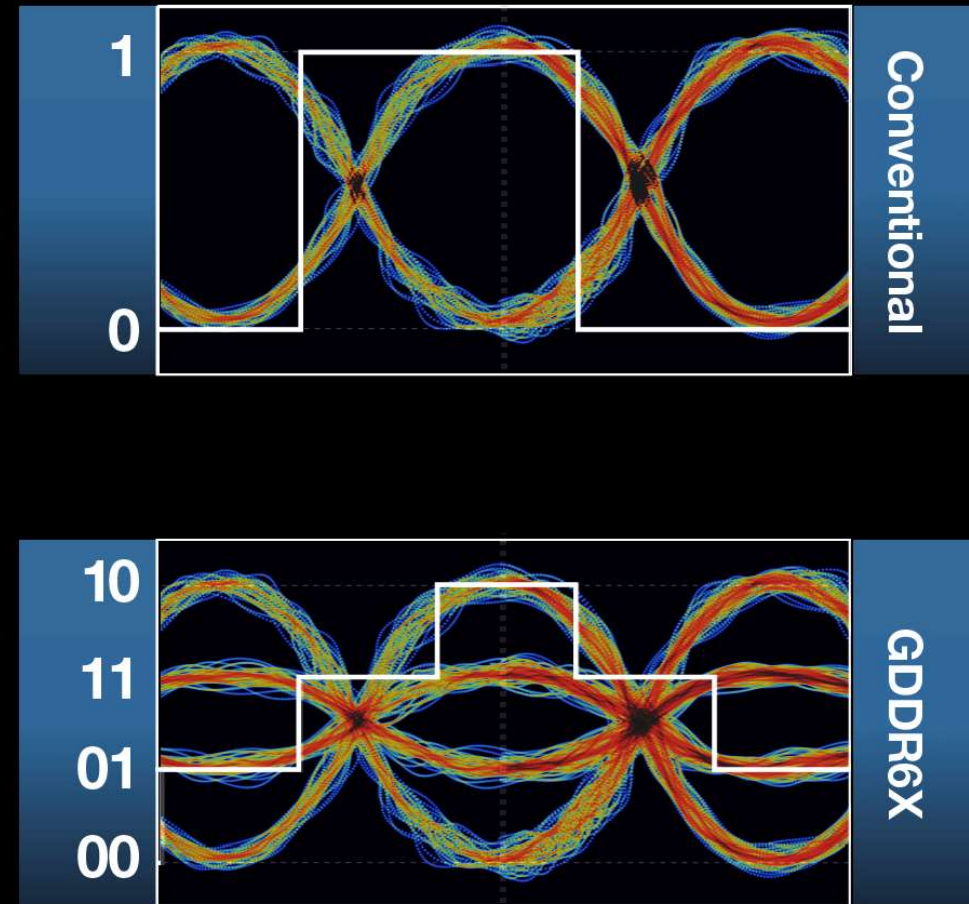
System Bandwidth



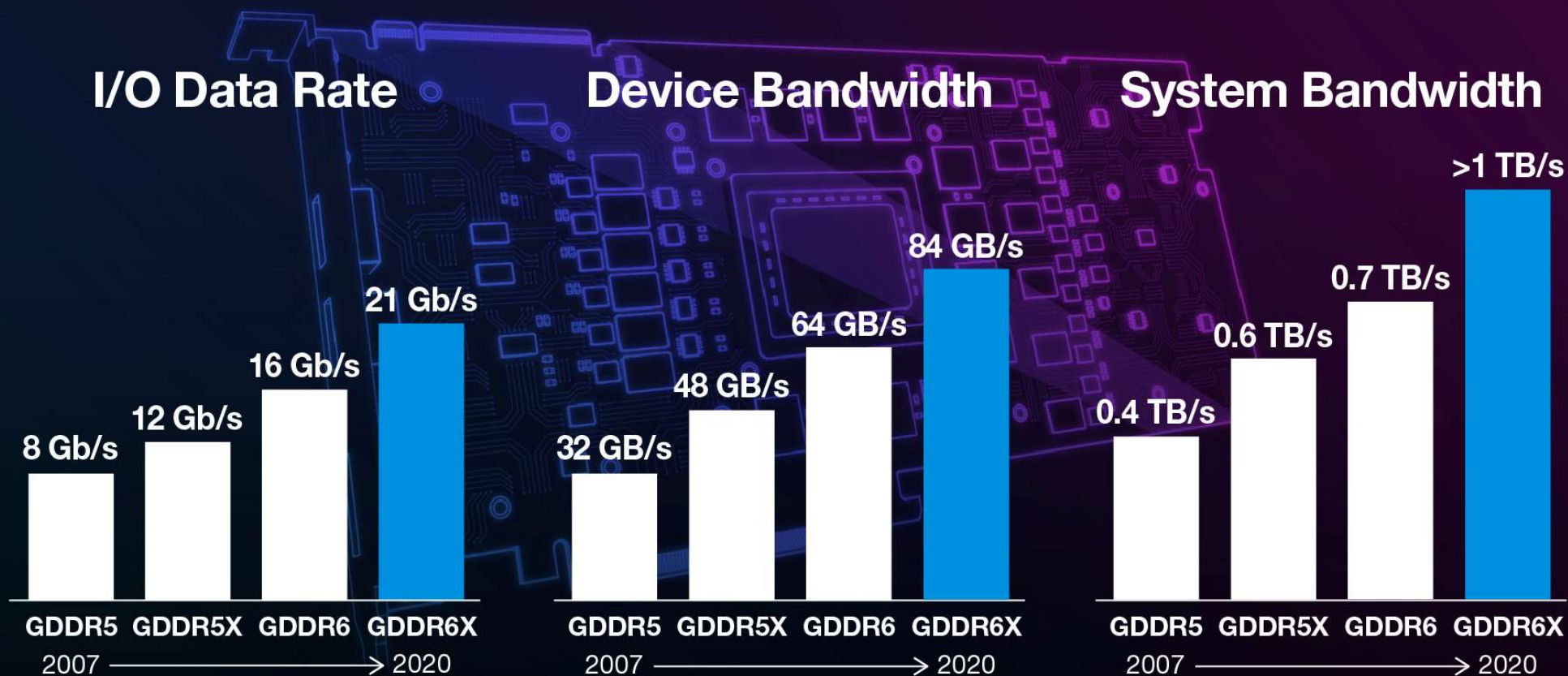


Doubling Data Down Every Wire

By using PAM4 multilevel signaling, Micron GDDR6X transfers more data and at a much faster rate, moving two bits of information at a time to double the I/O data rate.



Delivering Ultra-Bandwidth



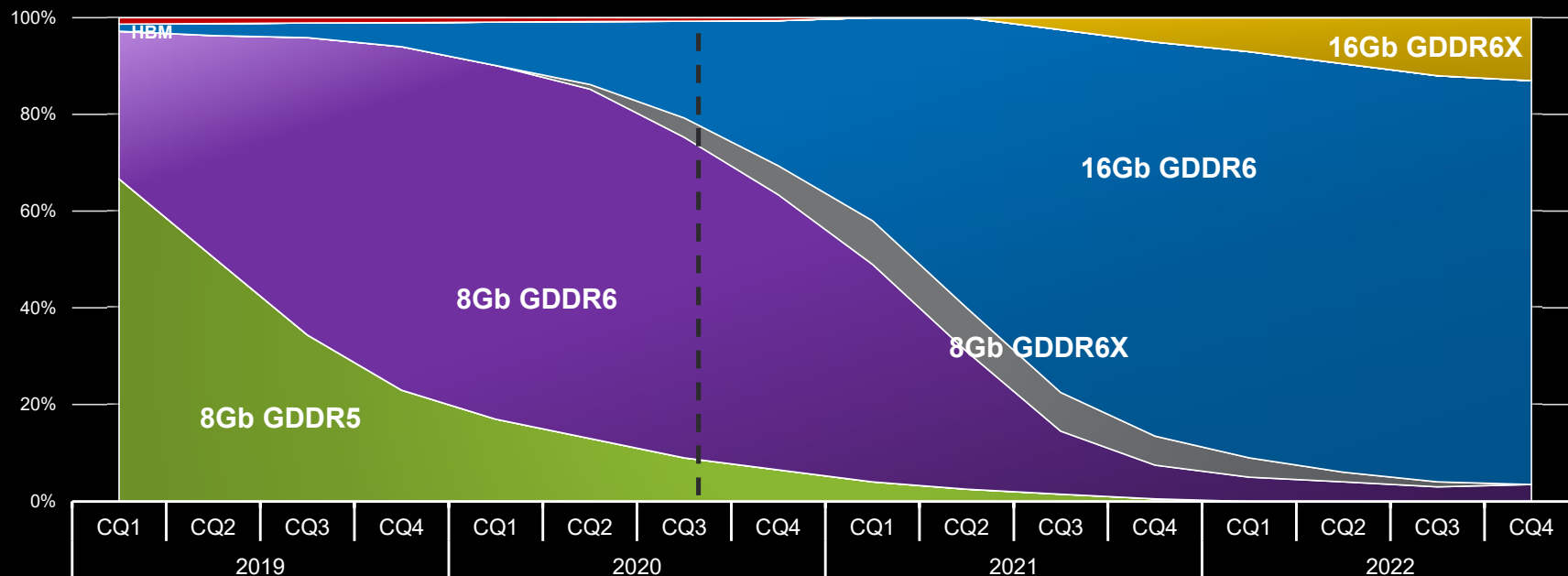
High Performance DRAM Comparison

	Standard DRAM				Ultra-Bandwidth Solutions			
Type	DDR4	DDR5*	LPDDR4/X	LPDDR5*	GDDR5	GDDR6	GDDR6X	HBM2E
Die Density	Up to 16Gb	Up to 64Gb	Up to 32Gb	Up to 32Gb	Up to 8Gb	Up to 32Gb	Up to 16Gb	16 Gb 4-H and 8-H
Prefetch Size	8n	16n	16n	16n/32n	8n	16n	16n	4n
Voltage (Vdd)	1.2V	1.1V	1.1V	1.05V	1.5V and 1.35V	1.35V and 1.25V	1.35V and 1.25V	1.2V
I/O Voltage (Vddq)	Same as VDD	Same as VDD	1.1/0.6V	0.5V	Same as VDD	Same as VDD	Same as VDD	Same as VDD
Max Data Rate	Up to 3.2Gbps	Up to 6.4Gbps	Up to 4.26Gbps	Up to 6.4Gbps (investigating > 6.4Gbs)	Up to 8.0 Gbps	Up to 16.0 Gbps (>16Gbps in planning)	21 Gbps (>21 Gbps in planning)	Up to 3.2Gbps
Burst Length	BC4, 8	BC8,16	16, 32	16,32	8	16	8 in PAM4 mode 16 in RDQS mode	4
Device Width (I/O)	x4, x8, x16	X4/x8/x16	2Ch x16	x8/x16	x32/x16	2ch x16/x8	2ch x16/x8	x1024
Internal Banks	16 (x4/x8) 8 (x16)	32(x4/x8) 16(x16)	8/Ch	16	16	16	16	16 (4-H), 32 (8-H)
Bank Groups	4 (x4/x8) 2 (x16)	8(x4/x8) 4(x16)	N/A	4	N/A	4	4	4 or 8
Key Timing Parameters								
Data Rate	3.2Gbps	4.8Gbps	4.26Gbps	6.4Gbps	8.0Gbps	16.0Gbps	19 Gbps, 21 Gbps	3.2Gbps
Read Latency (tAA)	~12.5 – 15ns	~15 – 18.33ns	~17	~22ns	~15 ns	~15 ns	~15ns	~25 ns
Row Cycle Time (tRC)	45 - 47ns	47-50.3	60 - 63ns	60 to 63ns	40- 45ns	40- 45 ns	40-45ns	45ns
Bank Address Delays (tRRD/tFAW)	2.5–6.4ns/ 10-30ns	1.67-5ns/ 13.3-16.7ns	10ns/ 40ns	5ns/ 20ns	4ns/ 16ns	2.5ns/ 10ns	2ns/ 8ns	2.5ns/ 10ns
Bus Turn Delay (tWTR)	2.5 – 7.5ns	2.5 - 10ns	10ns	12ns	5ns	5ns	5ns	5.4ns
Energy per bit (est.)	10pJ/bit	6pJ/bit	5pJ/bit	4pJ/bit	9pJ/bit	8.5pJ/bit	7.25pJ/bit	6pJ/bit
Self refresh power (IDD6R)	24mW	TBD	< 1mW	< 1mW	20mW	40mW	NA	TBD

Graphic Card Market Transition (Volume 1Gb equivs)

Key Points

- 8Gb is main density from 2017-2020
- 16Gb GDDR6 intro in CY19, larger adoption from 2H2020
- GDDR6X intro in 2H'20 drives performance leadership
- 2021: 16Gb GDDR6 becomes market driver in volume
- 2020: 8Gb GDDR5 remaining in some legacy platforms



Market Segmentation

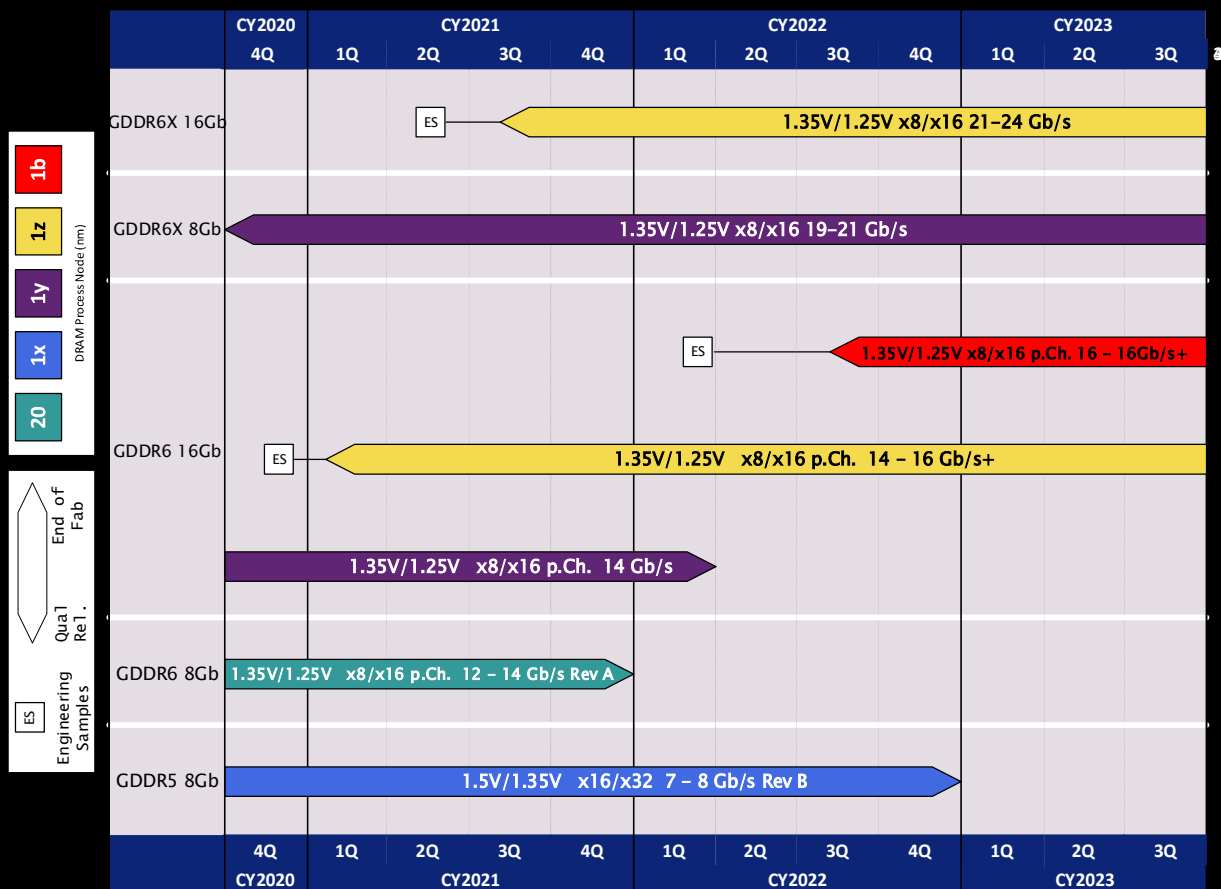
High End/Enthusiast

Performance

Mainstream/Value

	2019	2020	2021	2022
High End/Enthusiast	8Gb GDDR6: 14-16Gb/s	8Gb GDDR6X: 19-21Gb/s 16Gb GDDR6: 16Gbps	16Gb GDDR6X: 21-24Gb/s 16Gb GDDR6: 16Gbps	16Gb GDDR6X: 21-24Gb/s
Performance	8Gb GDDR6: 12-14Gb/s 8Gb GDDR5: 8Gb/s	8Gb/16Gb GDDR6: 14Gb/s	16Gb GDDR6: 14-16Gb/s	16Gb GDDR6: 16Gb/s
Mainstream/Value	8Gb GDDR6 GDDR5	8Gb GDDR6 GDDR5	8Gb/16Gb GDDR6	16Gb GDDR6

Graphics DRAM Roadmap – Nov'20



Micron Confidential

Key Points

GDDR6X

- FBGA 180, 0.75mm; VDD 1.35V
- 8Gb (1ynm): 19-21 Gb/s
 - MP CQ3'20
- 16Gb (1znm): 21-24 Gb/s
 - MP CQ3'21

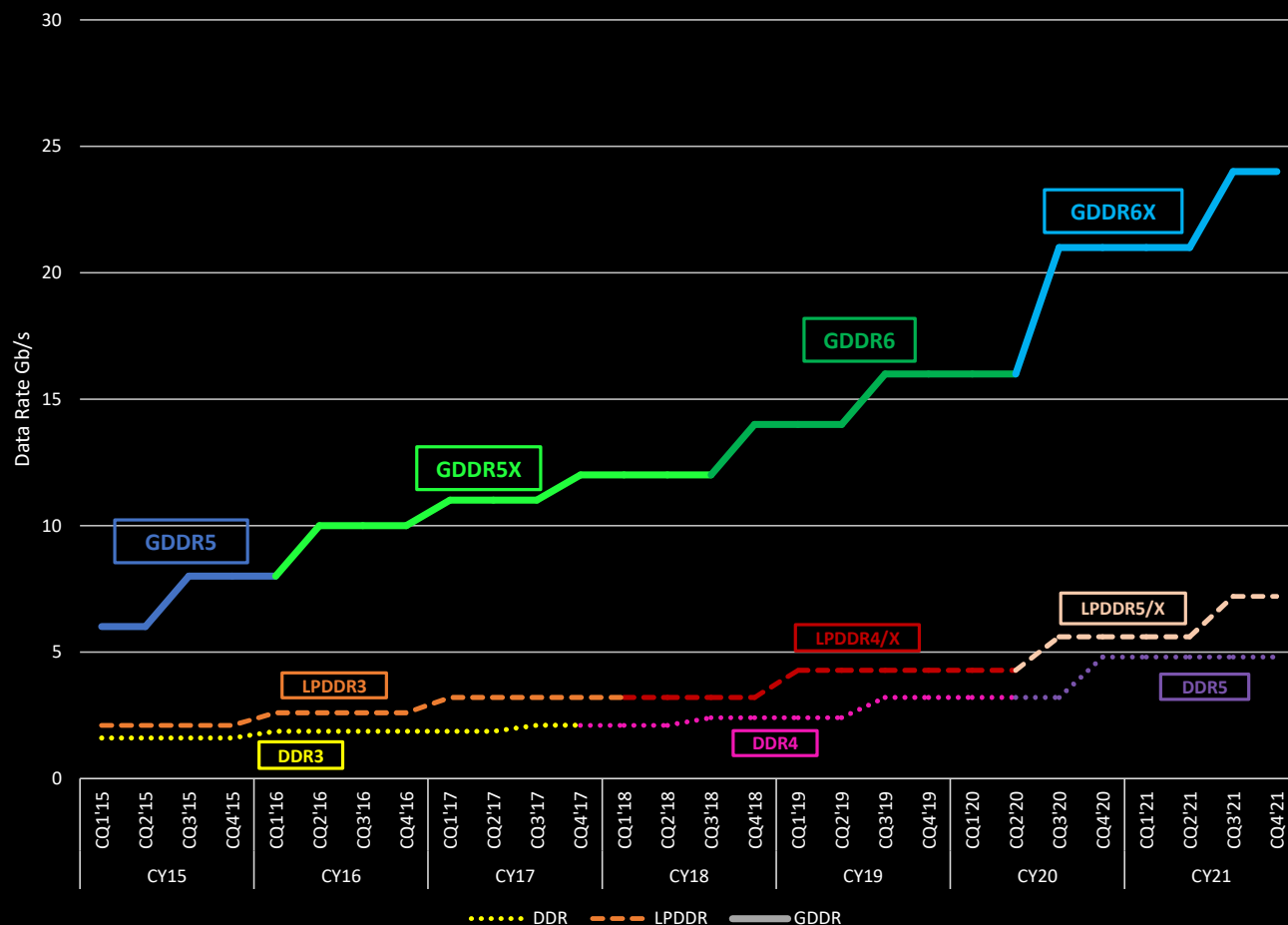
GDDR6

- FBGA 180, 0.75mm; VDD 1.35V / 1.25V
- 16Gb (1ynm): 14 Gb/s
 - in mass production
- 16Gb (1znm): 14-16 Gb/s+
 - ES 12/2020
 - CS 1/2021
- 16Gb (1bnm): 16-16 Gb/s+
 - Ramp in CY22
 - OD-ECC
- 8Gb (20nm): 12-14 Gb/s
 - EOL end of CY21

GDDR5

- 8Gb (1xnm): 7.0 - 8.0 Gb/s
 - 1.35V support up to 8Gbps

Top Performance by a Memory Technology



Key Points

GDDR5

- 8Gb 8Gbps MP now

GDDR5X – EOLed

GDDR6

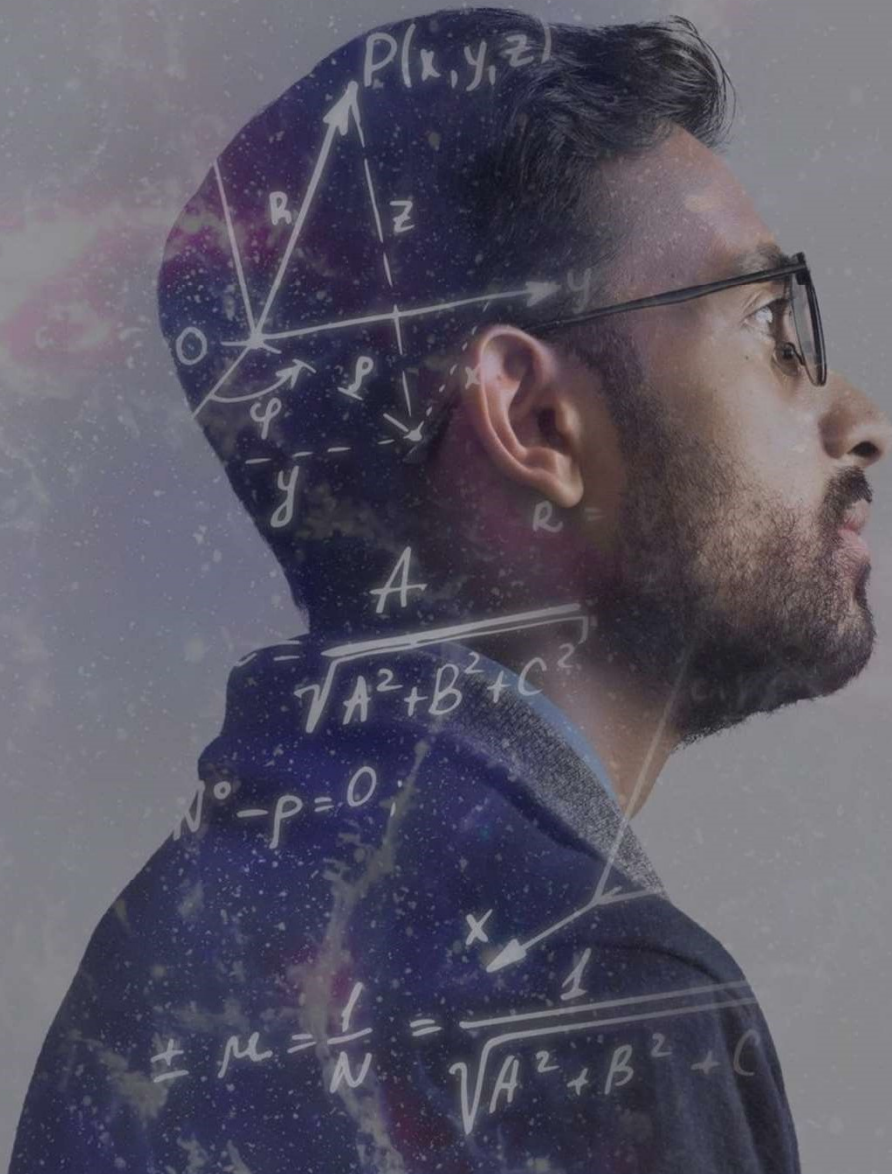
- 8Gb 16Gbps MP now
- 16Gb 16Gbps MP now

GDDR6X

- 8Gb 19Gbps MP now
- 8Gb 21Gbps MP now
- 16Gb 21Gbps in 2H'21
- 16Gb 24Gbps in 2H'21

GDDR7

- ~CY23



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